

**CHIP STRUCTURE WITH PADS HAVING BUMPS OR WIREBONDED WIRES  
FORMED THEREOVER OR USED TO BE TESTED THERETO**

Appl. No. : 10/730,834 Confirmation No.  
Applicant : Nick Kuo,  
Chiu-Ming Chou,  
Chien-Kang  
Chou,  
Chu-Fu Lin  
Filed : December 8, 2003  
TC/A.U. : 2826  
Examiner : ANDUJAR,  
LEONARDO  
Docket No. : MEGP0033USA  
Customer No. : 27765

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION**

5 Sir:

In response to the Final Office Action mailed January 24, 2007, please amend the above-identified application and consider the remarks as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 9 of this paper.